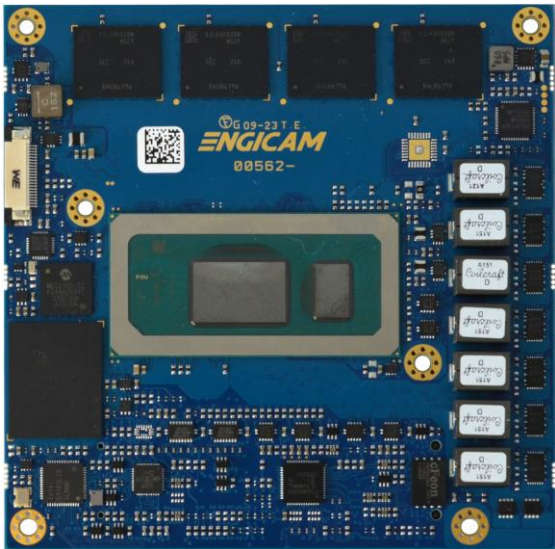


The new Engicam COMe module, based on Intel® processors ALDER LAKE for IoT applications with performance architecture, enables IoT use cases with up to 1.36x times faster in single-thread performance and up to 1.35x times faster in multi-thread performance vs. the previous generation processors.



HIGHLIGHTS

- Standard COM Express
- Suitable for IoT and real time performance
- Ethernet interface up to 2.5 Gb
- DP/HDMI up to 4096x2160@60Hz

APPLICATIONS



FEATURES

	CPU	• Intel Core i7-12800HE Core @2.4 GHz (burst 4.6 GHz) 24MB L3 cache, 45W • Intel Core i5-12600HE Core @ 2.5 GHz (burst 4.5 GHz) 18MB L3 cache, 45W • Intel Core i3-12300HE Core @ 1.9 GHz (burst 4.3 GHz) 12MB L3 cache, 45W • Intel Core i7-1270PE Core @ 1.2 GHz (burst 4.5 GHz) 18MB L3 cache, 28W • Intel Core i5-1250PE Core @ 1.2 GHz (burst 4.4 GHz) 12MB L3 cache, 28W • Intel Core i3-1220PE Core @ 1.1 GHz (burst 4.2 GHz) 12MB L3 cache, 28W • Intel Core i7-1265UE Core @ 1.2 GHz (burst 4.7 GHz) 12MB L3 cache, 15 W • Intel Core i5-1245UE Core @ 1.1 GHz (burst 4.4 GHz) 12MB L3 cache, 15 W • Intel Core i3-1215UE Core @ 0.9 GHz (burst 4.4 GHz) 10MB L3 cache, 15 W • Intel Celeron 7305E Core @ 1 GHz 8MB L3 cache, 15 W
	CORES	Up to 6 P-Cores Up to 8 E-Cores
	MEMORY	Up to 64 GB LPDDR5 5200 MT/s
	GRAPHICS	• Intel® Iris Xe Graphics architecture • Intel® Deep Learning Boost (VNNI) • DirectX 12.1, OpenGL 3.0, IPU 6.0
	VIDEO INTERFACES	• HDMI/DP • eDP/LVDS
	VIDEO PROCESSING	• HEVC/H.265, AVC/H.264, VP9, JPEG/MJPEG dec • HEVC/H.265, AVC/H.264, VP9, JPEG enc
	NETWORKING	Ethernet interface up to 2.5 Gb

	MASS STORAGE	• 2x SATA • Starting from 64GB NVMe PCIe
	USB	• 4 x USB HOST 3.1 • 8 x USB HOST 2.0
	PCIe	• Up to 8x PCIe 3.0 • Up to 8x PCIe Gen 4 (PEG) + 4x PCIe 4.0 PEG (optional)
	PERIPHERAL INTERFACES	SM Bus, I2C, LPC/eSPI (option), UART, GPIOs, CSI connector, JTAG EC connector
	AUDIO	HDA Interface
	OPERATING SYSTEM	• Ubuntu • Windows 10
	POWER SUPPLY	+8.5 to 20 V DC
	DIMENSIONS	95 x 95 mm
	OPERATING TEMPERATURE*	Commercial (0°C to 100°C Tj)

* Valid for all components except CPU. Customer shall consider junction temperature for CPU. Temperature will widely depend on application. Specific cooling solutions could be necessary for the final system.

BLOCK DIAGRAM

